

bq27510EVM System-Side, Single-Cell Impedance Track™ Technology Evaluation Module

This evaluation module (EVM) is a complete evaluation system for the bq27510. The EVM includes one bq27510 circuit module, a current sense resistor, one thermistor, an EV2300 PC interface board for gas gauge interface, a PC USB cable, and Windows[™]-based PC software. The circuit module includes one bq27510 integrated circuit and all other onboard components necessary to monitor and predict capacity for a system-side fuel gauge solution. The circuit module connects directly across the battery pack. With the EV2300 interface board and software, the user can read the bq27510 data registers, program the chipset for different pack configurations, log cycling data for further evaluation, and evaluate the overall functionality of the bq27510 solution under different charge and discharge conditions.

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Features

1 Features

- Complete evaluation system for the bq27510 gas gauge with Impedance Track[™] technology
- Populated circuit module for quick setup
- Personal computer (PC) software and interface board for easy evaluation
- Software that allows data logging for system analysis

1.1 Kit Contents

- bq27510 circuit module (HPA329)
- EV2300 PC interface board
- USB connection cable to interface board
- NTC103AT thermistor
- Set of support documentation

1.2 Ordering Information

Table 1. Ordering Information

EVM PART NUMBER	CHEMISTRY	CONFIGURATION	CAPACITY
bq27510EVM	Li-ion	1 cell	Any

2 bq27510-Based Circuit Module

The bq27510-based circuit module is a complete and compact example solution of a bq27510 circuit for battery management. The circuit module incorporates a bq27510 battery gas gauge integrated circuit (IC) and all other components necessary to accurately predict the capacity of 1-series Li-ion cell.

2.1 Circuit Module Connections

Contacts on the circuit module provide the following connections:

- Direct connection to the battery pack (J1 or J2): PACK+, PACK-, and TS
- To the serial communications port (J5): SDA, SCL, and VSS
- The system load and charger connect across charger and load (J3 and J4): CHARGER+/LOAD+ and CHARGER-/LOAD-.
- Access to signal outputs (J6): BAT_LOW and BAT_GD

2.2 Pin Descriptions

PIN NAME	DESCRIPTION
PACK+	Pack positive terminal
PACK-	Pack negative terminal
TS	Pack thermistor input
SDA	I ² C [™] communication data line
SCL	I ² C communication clock line
VSS	Signal return for communication line, shared with charger and ground

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PIN NAME	DESCRIPTION
CHG+/LOAD+	High potential of load or charger connection
CHG-/LOAD-	Low potential of load or charger connection (system VSS)
BAT_LOW/BAT_GD	Access to open-drain output that is configurable to function as a Battery Good or a Battery Low signal.

3 bq27510 Circuit Module Schematic

3.1 Schematic

The schematic follows the bill of materials in this user's guide.

4 Circuit Module Physical Layouts and Bill of Materials

This section contains the board layout, bill of materials, and assembly drawings for the bq27510 circuit module.

4.1 Board Layout

This section shows the PCB layers (Figure 1 through Figure 4), and assembly drawing for the bq27510 module.



Figure 1. bq27510EVM-001 Layout – Silk Screen







Figure 3. Top Layer



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Figure 4. Bottom Layer

4.2 Bill of Materials and Schematic

Table 2. Bill of Materials

Count	Ref Des	Description	Size	Manufacturer	Part No.
6	C1, C2, C4, C5, C6, C7	Capacitor, Ceramic, 0.1uF, 10V, X5R	402	Murata	GRM155R61A104KA01D
1	C3	Capacitor, Ceramic, 0.47uF, 6.3V, X5R	402	Murata	GRM155R60J474KE19D
2	C8, C9	Capacitor, Ceramic, 150pF, 50V, NPO, 5%	402	Murata	GRM1555C1H151JA01D
2	J1, J5	Header, Friction Lock Ass'y, 4-pin Right Angle	0.400 x 0.500	Molex	22-05-3041
1	J2	Terminal Block, 4-pin, 6-A, 3.5mm	0.55 x 0.25 inch	OST	ED555/4DS
3	J3, J4, J6	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	OST	ED555/2DS
1	R1	Resistor, Chip, 0.01-Ohms, 0.25W, 1%	1206	Vishay	WSL1206R0100FEA
2	R13, R14	Resistor, Chip, 10k-Ohms, 1/16-W, 5%	402	Std	Std
1	R2	Resistor, Chip, 1.80-MOhms, 1/16-W, 5%	402	Std	Std
4	R3, R4, R11, R12	Resistor, Chip, 100-Ohms, 1/16-W, 5%	402	Std	Std
1	R5	Resistor, Chip, 18.2-kOhms, 1/16-W, 5%	402	Std	Std
1	R6	Resistor, Chip, 1-kOhms, 1/16-W, 5%	402	Std	Std
2	R7, R8	Resistor, Chip, 300-Ohms, 1/16-W, 5%	402	STD	STD
2	R9, R10	Resistor, Chip, 1-MOhms, 1/16-W, 5%	402	Std	Std
4	TP1, TP2, TP3, TP4	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	Keystone	5001
1	U1	IC, Host-Side Impedance-Track Fuel Gauge	QFN12	ТΙ	BQ27510DRZ

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Figure 5. Schematic



EVM Hardware and Software Setup

4.3 bq27510 Circuit Module Performance Specification Summary

This section summarizes the performance specifications of the bq27510 circuit module.

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Specification	Min	Тур	Max	Units
Input voltage Pack+ to Pack-	2.7	3.6	4.3	V
Charge and discharge current	0	1	2	А

Table 3. Performance Specification Summary

5 EVM Hardware and Software Setup

This section describes how to install the bq27510EVM PC software and how to connect the different components of the EVM.

5.1 System Requirements

The bq27510EVSW software requires Windows 2000 or Windows XP. Drivers for Windows 98SE are provided, but Microsoft[™] no longer supports Windows 98; therefore, Windows 98 can have issues with USB driver support. The EV2300 USB drivers have been tested for Windows 98SE, but no assurance is made for problem-free operation with specific system configurations.

5.2 Software Installation

Find the latest software version in the bq27510 tool folder on <u>power.ti.com</u>. Make a search by Part Number for bq27510 to access the tool folder. Use the following steps to install the bq27510EVSW software:

- 1. Ensure that the EV2300 is not connected to the personal computer (PC) through the USB cable before starting this procedure.
- 2. Open the archive containing the installation package, and copy its contents into a temporary directory.
- 3. Open the software file that was downloaded from the TI Web site.
- 4. Follow the instructions on screen until completing the software installation.
- 5. Before starting the evaluation software, connect the EV2300 to the computer using the USB cable.
- 6. Wait until system prompt "new hardware found" appears. Choose "select location manually", and use the "browse" button to point to subdirectory TIUSBWin2K-XP-1.
- 7. Answer "continue" to the warning that drivers are not certified with Microsoft[™].
- 8. After installation finishes, another system prompt "new hardware found" appears. Repeat steps 1 through 5, but specify the directory as TIUSBWin2K-XP-2.
- 9. Answer "continue" to the warning that drivers are not certified with Microsoft. Driver installation is now finished.

6 Troubleshooting Unexpected Dialog Boxes

The user that is downloading the files must be logged in as the administrator.

The driver is not signed, so the administrator must allow installation of unsigned drivers in the operating system policy.

7 Hardware Connection

The bq27510EVM-001 comprises three hardware components: the bq27510 circuit module, the EV2300 PC interface board, and the PC.

7.1 Connecting the bq27510 Circuit Module to a Battery Pack

Figure 6 shows how to connect the bq27510 circuit module to the cells and system load/charger.



Figure 6. bq27510 Circuit Module Connection to Cell and System Load/Charger

7.2 PC Interface Connection

The following steps configure the hardware for interface to the PC.

1. Connect the bq27510-based EVM to the EV2300 using wire leads as shown in Table 4.

Table 4. Circuit Module to EV2300 Connections

bq27510-Based Battery	EV2300
SDA	SDA
SCL	SCL
VSS	GND

2. Connect the PC USB cable to the EV2300 and the PC USB port.

The bq27510EVM-001 is now set up for operation.



8 Operation

This section details the operation of the bq27510 EVSW software.

8.1 Starting the Program

Run bq27510 EVSW from the Start | Programs | Texas Instruments | bq Evaluation Software menu sequence. The DataRAM screen (Figure 7) appears. Data begins to appear once the <Refresh> (single time scan) button is clicked, or when the <Keep Scanning> check box is checked. To disable the scan feature, deselect <Keep Scanning>.

The continuous scanning period can be set via the | Options | and | Set Scan Interval | menu selections. The range for this interval is 0 ms to 65,535 ms. Only items that are selected for scanning are scanned within this period.

The bq27510 EVSW provides a logging function which logs the values that were last scanned by EVSW. To enable this function, select the *Start Logging* button; this causes the *Keep Scanning* button to be selected. When logging is *Stopped*, the keep scanning button is still selected and has to be manually unchecked.

The logging intervals are specified under the | Options | menu with the maximum value of 65,535 ms. The *Log* interval cannot be smaller than the scan interval because this results in the same value being logged at least twice.

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Figure 7. DataRAM Screen

This screen (Figure 7) shows the RAM data set. Additional Flag and Status data can be viewed at the bottom of the DataRAM screen.

Dragging the splitter bar (line that separates the Flags/Status data from Data Ram register values) changes the height of the Flags/Status Data display. Selecting | View |, then | Auto Arrange | returns the splitter bar to its original location.

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Operation

8.2 Setting Programmable bq27510 Options

The bq27510 data flash comes configured per the default settings detailed in the bq27510 data sheet. Ensure that the settings are correctly changed to match the pack and application for the bq27510 solution being evaluated.

IMPORTANT: The correct setting of these options is essential to get the best performance.

The settings can be configured using the Data Flash screen (Figure 8).

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a sta	Calibration	<u>γ</u>	Security						
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	Name	Value	Unit	Name	Value	Unit	Name	Value	Unit
aRAM	Safety	-	-	Delta Temp	5.0	°C	Device Name	bq27510	-
	OT Cha	55.0	°C	Suspend Low Temp	-5.0	°C	Discharge	10000	-
	OT Chg Time	2	Sec	Suspend High Temp	55.0	°C	SOC1 Set Threshold	150	mAh
	OT Chy Recovery	50.0	°C	Charge Termination		2	SOC1 Clear Threshold	175	mAh
ata	OT Dsg	60.0	°C	Toper Current	100	mA	SOCF Set Threshold	75	mAh
	OT Dsg Time	2	Sec	Min Taper Capacity	25	mAh	SOCF Clear Threshold	100	mAh
ash	OT Dsg Recovery	55.0	°C	Taper Voltage	100	mV	Registers	4	
	Charge Inhibit Cfg	-		Current Taper Window	40	Sec	Op Config	0979	flg
	Chg Inhibit Temp Low	0.0	°C	Data	-	-	Power	-	-
C Pro	Chg Inhibit Temp High	45.0	°C	Initial Standby	-10	mA	Flash Update OK Voltage	2800	mV
- Pro	Temp Hys	5.0	°C	Initial MaxLoad	-500	mA	Sleep Current	10	mA
	Charge		-	CC Threshold	900	mAh	Hibernate I	8	mA
	Charging Voltage	4200	mV	Design Capacity	1000	mAh	Hibernate V	2550	mV
A5Y									

Figure 8. Data Flash Screen

To read all the data from the bq27510 data flash, click on menu option | Data Flash | Read All |.

To write to a data flash location, click on the desired location, enter the data and press <Enter>, which writes the entire tab of flash data, or select menu option | Data Flash | Write All |. The data flash must be read before any writes are performed to avoid any incorrect data being written to the device.

The | File | Special Export | menu options allows the data flash to be exported, but it configures the exported data flash to a learned state ready for mass production use.

The data-flash configuration can be saved to a file by selecting | File | Export | and entering a file name. A data-flash file also can be retrieved in this way, imported, and written to the bq27510 using the | Write All | button.

The module calibration data is also held in the bq27510 data flash.

The bq27510 allows for an automatic data-flash export function, similar to the DataRAM logging function. This feature, when selected via | Options | Auto Export |, exports Data Flash to a sequential series of files named as *FilenameNNNNN.gg* where N = a decimal number from 0 to 9.

The AutoExport interval is set under the | Options menu | with a minimum value of 15 s. The AutoExport filename is also set under the | Options menu |.

When a check is next to | AutoExport |, the AutoExport is in progress. The same menu selection is used to turn on/off AutoExport.

If the Data Flash screen is blank, then the bq27510 that is being used may not be supported by the bqEVSW version that is being used. An upgrade may be required.



9 Calibrate Screen

To ensure proper calibration, perform the following steps. These steps may or may not be required, depending on the type of calibration being performed.

9.1 To Calibrate the bq27510

Select the types of calibration to be performed (see Figure 9).

Enter the measured values for the types selected.

If Temperature Calibration is selected, then select the sensor that is to be calibrated.

Press the Calibrate Part as indicated below button.

9.2 CC Offset Calibration

This performs the internal calibration of the coulomb counter input offset.

9.3 Board Offset Calibration

This performs the offset calibration for the current offset of the board.

It is expected that no current is flowing through the sense resistor while performing this calibration step. Remove load and short PACK– to LOAD–.

Press the CC Board Offset Calibration button.

9.4 Voltage Calibration

- Measure the voltage across Pack+ and Pack-.
- Type the voltage value in mV into Enter Actual Voltage .
- Press the Calibrate Part as indicated below button.

9.5 Temperature Calibration

- Measure the temperature for PACK.
- Type the temperature value into *Enter Actual Temperature*.
- Select if the temperature sensor to calibrate is the internal or external.
- Press the Calibrate Part as indicated below button.

9.6 Pack Current Calibration

- Connect a load to LOAD- and LOAD+ that draws approximately 1 A, or connect a current source to LOAD- and Pack-.
- Measure the current and type value into *Enter Actual Current* using (-) for current in discharge direction.
- Press the Calibrate Part as indicated below button.



dow Help		R = 4		SIGNAL PROCESSING"	
Please ensure that sca CC Board Offset	nning/communication i			STURAL PHILESSING	
Calibrate Part as indicated below	1				
CC Offset Calibration					
Voltage Calibration	Measured voltage 4141 mV	Enter actual voltage	Cell Count	Ensure voltage reference is stable. Calibration with cells connected is not recommended unless cells are in a state of rest. Set current=0 for accuracy.	
Temperature Calibration	Measured temperature	Enter actual temperature	Int. Sensor ✓ Ext. Sensor 1		
Pack Current Calibration	Measured current 0 mA	Enter actual current -1000 mA		Apply a 1 Ampere discharge load. Discharge current is a negative value.	

Figure 9. Calibration Screen



10 I2C Pro Screen

10.1 I²C Communication

The read/write operations of the I2C Pro function is not specific to any gas gauge. These operations serve as general-purpose communication tools (Figure 10).

Texas Inst	uments by Gas Gauge Evaluation Software - by27510 v1.11 - [Pro screen: I2C over I2C	lines] 🔲 🗊 🔀
🎭 Eile 🛛 Window	v Help	- 6 ×
2117	TEXAS INSTRUMENTS R E A L W D B L D S I E N A L Caution: This screen is for advanced users. Some commands may cause permanent damage to hardware.	P R B C E S S I N S
X	All Values in hexadecimal(No prefix). I2C Address AA	
-		
DataRAM	Read I2C Data Block	
	12C Command 40 Read Data Size 05 Read Data	
Data		
Flash	Write I2C Data Block	
	12C Command 00 Data 0000 Write Data	
I2C Pro		
-		
Calibrate	Read/Write 12C Byte Byte Write Byte 12C Command 00 Byte Byte Write Byte	
	(12C. <u>Power</u>)	
bqEA5Y	bq275xx Programming (Not compatible with bq27350)	
	C:\userdata\MichaelVega\bq27501\srec\bq275 Program	
100%	Execute Program on bq8032	
	ICN Bead to "senc file	
Fuel Gauge 97%		
Communication 0	k	DF Task Progress: 100% Task Completed. 02:14:42 PM

Figure 10. I2C Pro Screen

11 bqEasy[™] Software

11.1 Introduction

Texas Instruments fuel gauges, employing the Impedance Track[™] algorithm offer an unmatched array of features and benefits. Sometimes, however, the wide range of configuration settings can seem challenging to get started with the evaluation process. In addition, determining the correct chemistry model and producing the 'golden image' file can be time consuming. The bqEASY program is designed to greatly simplify the process of configuring, calibrating, selecting chemistry, and performing learning cycles through the step-by-step use of a wizard program.

The bqEasy software runs inside the current EV software when it is executed by clicking the bqEasy button in the left column of buttons below the Calibrate button in the EV software.





Figure 11. bqEasy Welcome Screen

11.2 Program Navigation and Flowchart

The sequence of operation of the bqEASY[™] program can be understood by reviewing the basic flowchart in Figure 12. Using the program is simple – just start a new project and follow the steps sequentially from 1A to 5C. You can use the Next button, or click on the top tabs and left subsection labels to move to any desired page. Some operations must be completed in sequence due to data dependencies, or to implement the proper flow. Therefore, it is recommended that the prescribed sequence be followed, at least at first.

EXAS NSTRUMENTS



Figure 12. bqEasy[™] Flowchart

11.3 Simplified Configuration Procedures

These simplified configuration procedures can be used to quickly set up the parameters without navigating through the entire user interface.

- 1. Simple configuration of the gas gauge with default or custom data:
 - a. Open the current EV software, and click the bqEasy button in the left column of buttons below the "Calibrate" button in the EV software.
 - b. Click the "2. Configure" tab at the top row of bqEASY tabs. (Note: You can skip the first tab.)
 - c. Answer all questions, or leave defaults for all of tab "2", but be sure to click the "OK" button at the bottom of each tab "2" page to ensure that a Completion Checkmark appears for each page.



d. On page 2H, when you click the "OK" button, the software asks you to write to the data-flash memory. Click "Yes" for OK to write to the data flash.

Your Gas Gauge Module now has the data flash configured as you declared with all the information entered in tab "2. Configure".

- 2. Simple installation of the Chemistry data using bqEASY, if the chemistry is a known chemistry available in the bqEASY software:
 - a. Open the current EV software, and click the bqEasy button in the left column of buttons below the "Calibrate" button in the EV software.
 - b. Click the "4. Chemistry" tab at the top row of bqEASY tabs. (Note: You can skip all tabs prior to this.)
 - c. Either select "Use Default Chemistry", or click "Enable Chemistry Selection," and select the correct chemistry from the list.
 - d. If you cannot find the proper chemistry, check the device EVM tool folder on the TI Web site for any new bqChemistry file updates. These are updated more frequently than the EV software., Between EV software updates, TI creates a self-extracting installer and posts it in the EVM tool folder for the part being used. Install these updates if they are in the folder.

The software now configures all data-flash locations on Your Gas Gauge Module that deal with chemistry functions. No other data-flash locations are modified.

11.4 Files

The bqEASY software uses four types of files to configure a fuel gauge.

- 1. .ENCR These are default data-flash definition files found in the \bq_Evaluation_Software folder. The .ENCR file is basically a copy of the entire data flash from a fresh gas gauge prior to any data-flash updates either by the user or the gas gauge. They are unique for each version of each TI fuel gauge product. If you are working with a new version fuel gauge and an older version of bqEASY[™] software, the correct file may not be present. This requires a new version of the EV software with bqEASY[™] software. Navigate to the TI Web site in the EVM tool folder for the device being used, and download the latest version, or contact TI. For the bqEASY[™] program, the .ENCR files act mainly as a dictionary to look up the address for a given data-flash location. For bqEVSW, they define screen parameters including address, display formulas, and data type. An error message appears if the correct .ENCR file cannot be found.
- 2. .CHEM (Chemistry Files) These are read-only files found in the

..\bq_Evaluation_Software\Plugins\Chemistry folder of the application. When a new Li-Ion battery chemistry is developed, a new Impedance Track[™] model is required to define the chemical model. During automated chemistry selection, each of these files is scanned in order to select the best match with the recorded data. If you are working with a newly developed chemistry, it is possible that an acceptable match may not be found. If this is the case, check for updated bqEasy software or bqChemistry files on the TI Web site in the EVM tool folder for the part being used.

- 3. .DFI (Data-Flash Image Files) These are binary images of the fuel gauge data flash with modified values based on the application. Because of the binary format, it is quick and easy to transfer them to and from a gauge. Each fuel gauge model and firmware version has a unique read-only .DFI which is found in the ...bq_Evaluation_Software\Plugins\Device_Defaults folder of the application. During the bqEASY process, intermediate versions of .DFI files are recorded with current updated data in order to prevent the possibility of corruption. Then, the final output of bqEASY is also a .DFI file which is the 'golden image' that is programmed into each production unit. This output file is placed in the ...\bq_Evaluation_Software\Plugins\Projects folder.
- 4. **.EZY (bqEASY Project Files)** These are read-write text files which record header information regarding a project, answers to the wizard questions, and status regarding the stage of completion (the red check marks). They are kept in the ...\bq_Evaluation _Software\Plugins\Projects folder.



11.5 Completion Checkmarks

As the wizard questions and tasks are completed, completion checkmarks appear in two places – along the task list on the left and on the category tabs on top. A checkmark on a top tab only appears after all tasks in the category have been completed. For example, in Figure 8 all of the Setup tasks and all of the Configure tasks have been completed. Completion marks are saved in the .EZY project text file. When a completed or partially completed project file is opened, the user is given the chance to erase the checkmarks.

11.6 Device Detection

The bqEASY[™] program is designed to work with a fuel gauge present and already communicating with the bqEVSW evaluation software through the EV2300 USB interface. When the evaluation software is started, it reads the device type and displays it on the upper title block. This information is used by the bqEASY[™] program to select the correct default data-flash image (.DFI) and data-flash configuration file (.ENCR) for this particular device. To ensure that the device has not changed, bqEASY also checks the device type when the bqEASY button is pressed. If the correct files are not found, first check the TI Web site in the EVM tool folder for the part being used, and download the latest version of EV software with bqEASY[™] support. If that fails to help, contact TI.

1. Setup

As the wizard questions and tasks are completed, completion checkmarks appear in two places – along the task list on the left and on the category tabs on top. A checkmark on a top tab only appears after all tasks in the category have been completed. Completion marks are saved in the .EZY project text file. When a completed or partially-completed project file is opened, the user is given the chance to erase the checkmarks.

2. Configure

A series of eight screens is used to collect information about the battery pack application to enable automatic configuration of the most critical data-flash parameters.

3. Calibrate

If you wish to proceed with either automatic chemistry selection or *golden* unit learning cycles, the Impedance Track[™] fuel gauge must be accurately calibrated. The bqEASY screens simply ask the user to use the calibration screen of the bqEVSW for this purpose.

4. Chemistry

The chemistry choices presented in section 4B are based on files in the \Chemistry folder of the bqEASY application. The latest files are available for downloading from the ti.com Web site. Automation of the chemistry-selection cycle is made possible using a simple load and switch as depicted in Figure 13. The VOUT pin of the EV2300 may require a 1-M Ω pulldown resistor to ensure that switch is turned off when signaled to do so. The switch can be implemented with either a low VGS-threshold FET or a small relay such as the OMICRON G6RN-1 with a 5-Vdc coil. Multiple 2N7000 FETs can be paralleled if nothing else is available. The load can be either a power resistor or an electronic load set to a discharge rate of C/5. Hint: Follow the instructions exactly, or errors can result.

5. Cycle

When preparing for mass production, cell learning is required, but only on one *golden* pack. The chemical information learned from one pack is quickly transferred to all production units prior to calibration. Doing this correctly requires a series of charge and discharge cycles. The discharge part can be automated with the bqEASY[™] program if the simple load circuit for the chemistry selection is available. Follow the screen instructions.





Figure 13. Load and Switch

12 Related Documentation from Texas Instruments

To obtain a copy of any of the following TI documents, call the Texas Instruments Literature Response Center at (800) 477-8924 or the Product Information Center (PIC) at (972) 644-5580. When ordering, identify this document by its title and literature number. Updated documents can also be obtained through the TI Web site at www.ti.com.

 bq27510, System-Side Impedance Track[™] Fuel Gauge With Direct Battery Connection data sheet (<u>SLUS816</u>)

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During normal operation, some circuit components may have case temperatures greater than 60°C. The EVM is designed to operate properly with certain components above 60°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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